

09-17-2002



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DEPARTMENT OF COMMERCE
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Attorney Docket No.: 041501-5490

To the Commissioner for Patents

Please record the attached original documents or copy thereof.

ATTN: BOX ASSIGNMENT

1. Name of conveying party(ies):

1. Je Hoon PARK
2. Hee Bok KANG
3. Hun Woo KYE
4. Duck Ju KIM

Additional names of conveying party(ies) attached?

[] Yes [X] No

mrd
9/9/02

2. Name and address of receiving party(ies):

Name: Hynix Semiconductor Inc.

Internal Address:

Street Address: San 136-1, Ami-ri, Bubal-eub,
Ichon-shi, Kyoungki-do, Korea11002 U.S. PTO
10/23/2005

3. Nature of conveyance:

- [X] Assignment [] Merger
[] Security Agreement [] Change of Name
[] Other _____

City:

State:

Zip:

Additional name(s) & address(es) attached?

Execution Date: June 18, 2002

[] Yes [X] No

4. New Application number(s) or patent number(s): NEW APPLICATION

If this document is being filed together with a new application the execution date of the application is:

June 18, 2002A. Patent Application No.(s) 10237205 B. Patent No.(s)

Additional numbers attached: [] Yes [X] No

5. Name and address of party to whom
correspondence concerning document should be
mailed:

Name: Robert J. Gaybrick

Internal Address: Morgan, Lewis & Bockius LLP
Customer No. 09629

Street Address: 1111 Pennsylvania Avenue, NW

City: Washington State: D.C. Zip: 20004

6. Total number of applications and patents involved: 1

7. Total fee (37 C.F.R. §3.41): \$40.00

[] Enclosed

[X] Authorized to be charged to Deposit Account 50-0310

8. Deposit Account No. 50-0310

(Attach duplicate page if paying by deposit account)

9. Statement and Signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true
copy of the original document.

Robert J. Goodell Reg. No. 41,040

Name of Person Signing

Signature

September 9, 2002

Date

Total number of pages including cover sheet, attachments and documents: 3

09/16/2002 6TOM11 00000175 500310 10237205

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ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

**COLUMN REPAIR CIRCUIT IN
FERROELECTRIC MEMORY**

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on _____, (Serial No. _____); and

WHEREAS, Hynix Semiconductor Inc., a corporation of Korea, whose post office address is San 136-1, Ami-ri, Bubal-eub, Ichon-shi, Kyongki-do, Korea (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. _____, filed _____) the filing date and application number of said application when known. September 9, 2002

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of First Assignor Je Hoon PARK	Assignor's Signature <i>Je Hoon Park</i>	Date <i>June 18 2002</i>
Address Chongsolmaeul APT., 307-1403, 181, Kungok-dong, Pundang-gu, Songnam-shi, Kyonggi-do, Korea		Citizenship Republic of Korea
Full Name of Second Assignor Hee Bok KANG	Assignor's Signature <i>Hee Bok Kang</i>	Date <i>June 18 2002</i>
Address Yangji Town 3-401, 359-27, Toma-dong, So-gu, Daejeon-shi, Korea		Citizenship Republic of Korea

Names of additional inventors attached [X] Yes [] No

Morgan, Lewis & Bockius LLP

Full Name of Third Assignor	Assignor's Signature	Date
Hun Woo KYE	<i>Hun Woo Kye</i>	<i>June 18, 2002</i>
Address Ihwa APT., 101-1102, 97, Eungam-ri, Bubal-eub, Ichon-shi, Kyonggi-do, Korea		Citizenship Republic of Korea
Full Name of Fourth Assignor	Assignor's Signature	Date
Duck Ju KIM	<i>Duck Ju KIM</i>	<i>June 18, 2002</i>
Address 1048, Ihwa 2-dong, Cheju-shi, Cheju-do, Korea		Citizenship Republic of Korea

Names of additional inventors attached ☐ Yes ☒ No

Morgan, Lewis & Bockius LLP